

# 45V, 5.5mΩ, 80A, Single N-Channel

#### 1.Features

- ◆ 45V MOSFET technology
- ◆ Low on-state resistance
- Fast switching
- ♦ Vgs±20V

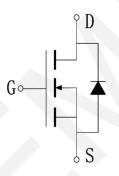
2.Ap	plica	ations
<b>4</b> .7	PIICC	1110113

- Power Switching Application
- Load Switching



Pin Description





Schematic Diagram

# 3.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V <sub>DSS</sub>	45	V
Gate to Source Voltage	V <sub>GSS</sub>	±20	V
Drain Current (DC)	I <sub>D</sub>	80	Α
Drain Current (Pulse), PW≤300μs	I <sub>DP</sub>	216	А
Total Dissipation	P <sub>D</sub>	100	W
Avalanche Energy, Single Pulsed	E <sub>AS</sub>	200	mJ
Junction Temperature	Tj	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### 4. Thermal Resistance Ratings

Parameter	Symbol	Value	Unit
Junction to case	Rejc	1.5	°C/W

Note 2: When mounted on 1 inch square copper board  $t \le 10$ sec The value in any given application depends on the user's specific board design.



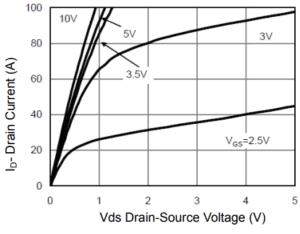
### 5.Electrical Characteristics at Ta=25°C (Note 3)

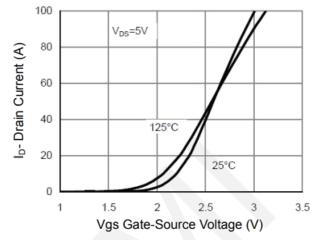
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	45	52		V
Zero-Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V			1	μΑ
Gate to Source Leakage Current	I <sub>GSS1</sub>	V <sub>GS</sub> = ±20V, V <sub>SS</sub> = 0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA	1	1.5	2.5	V
Static Drain to Source On-State Resistance	_	I <sub>D</sub> = 20A, V <sub>GS</sub> = 10V	-	5.5	7	mΩ
	R <sub>DS(on)</sub>	I <sub>D</sub> = 15A, V <sub>GS</sub> = 4.5V	-	8.5	12	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V, I <sub>D</sub> = 20A		20		s
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V,		3600		pF
Output Capacitance	Coss	V <sub>DS</sub> =25V, Frequency=1.0MHz		340		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			230		pF
Turn-ON Delay Time	t <sub>d(on)</sub>			12		ns
Rise Time	t <sub>r</sub>	$V_{DD} = 25V, R_L = 1\Omega$		30		ns
Turn-OFF Delay Time	t <sub>d(off)</sub>	$V_{GS} = 10V$ , $R_G = 3\Omega$		45		ns
Fall Time	t <sub>f</sub>			31		ns
	Qg	V <sub>DS</sub> = 25V,		65		nC
Total Gate Charge	Q <sub>gs</sub>	$V_{GS} = 10V$ ,		13		nC
	Q <sub>gd</sub>	I <sub>D</sub> = 20A		20		nC
Diode Forward Voltage	V <sub>FSD</sub>	I <sub>S</sub> = 20A, V <sub>GS</sub> = 0	0.4	0.8	1.2	V

Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

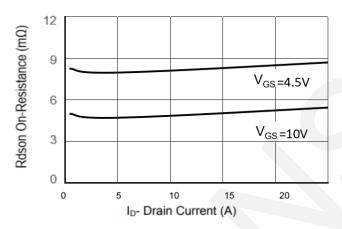


### 6. Typical electrical and thermal characteristics

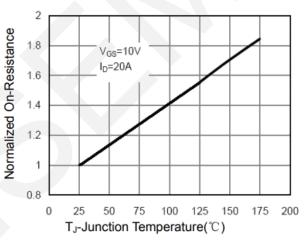




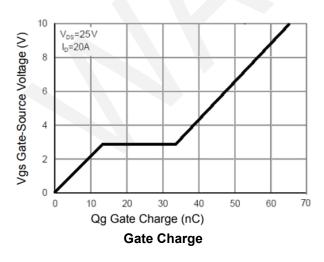
# **Output Characteristics**



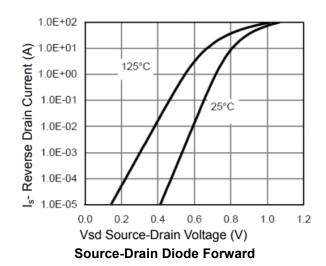
**Transfer Characteristics** 



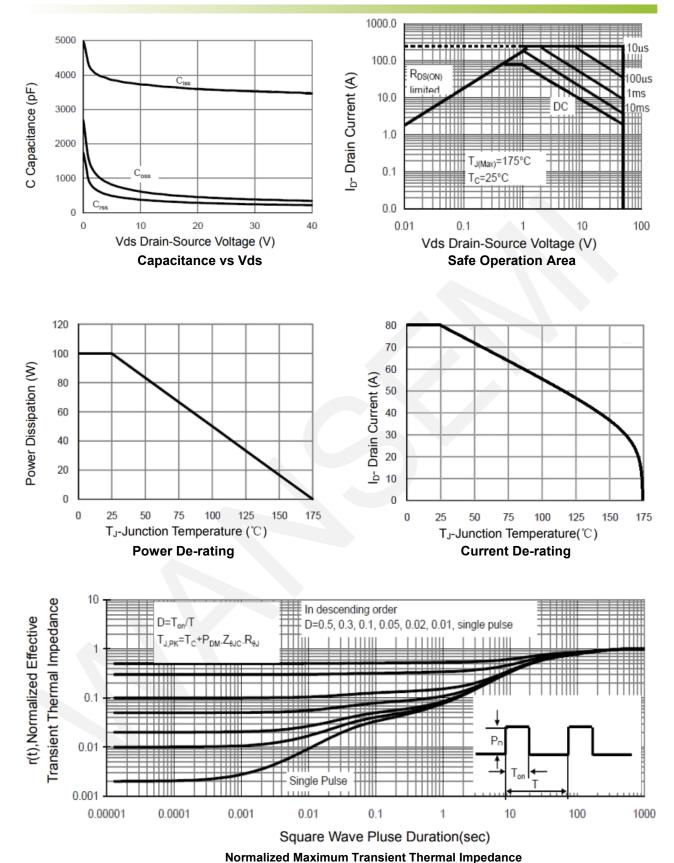
**Rdson-Drain Current** 



**Rdson-Junction Temperature** 

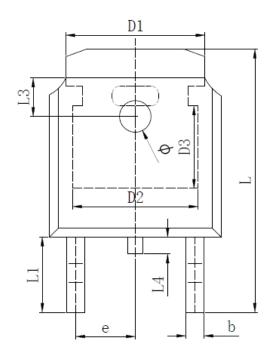


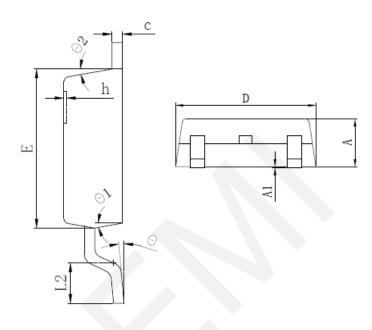






# 7.Package Dimensions





SYMBOL	MILLIMETER			
SIMDOL	MIN	Typ.	MAX	
A	2. 200	2. 300	2. 400	
A1	0.000		0. 127	
b	0.640	0.690	0.740	
c(电镀后)	0.460	0. 520	0. 580	
D	6. 500	6.600	6. 700	
D1	5. 334 REF			
D2	4.826 REF			
D3	3.166 REF			
Е	6. 000	6. 100	6. 200	
е	2.286 TYP			
h	0.000	0. 100	0. 200	
L	9. 900	10. 100	10. 300	
L1	2.888 REF			
L2	1.400	1.550	1. 700	
L3	1.600 REF			
L4	0.600	0.800	1.000	
ф	1. 100	1. 200	1. 300	
θ	0°		8°	
θ1	9° TYP			
θ2	9° TYP			



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